

PATENT

Docket No. MTI-31608

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant : Hock Chuan Tan, et al.  
Serial No. : **10/068,159**  
Filing Date : February 5, 2002  
For : Stacked Die in Die BGA Package  
Group Art Unit : 2818  
Confirmation No. : 8043  
Examiner : Thao P. Le

**CERTIFICATION OF SUBMISSION**

I hereby certify that, on the date shown below, this correspondence is being transmitted via the Patent Electronic Filing System (EFS) addressed to Examiner LE at the U.S. Patent and Trademark Office.

Date: May 4, 2007 JM K. Palmatier

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**COMMUNICATION**

Sir:

Examiners Le and Smith are thanked for the courtesies extended to the undersigned Attorney in their telephone conferences of May 2-3, 2007.

As discussed with Examiner Smith, enclosed herewith is an **Application Data Sheet**, which includes the information for the claim for foreign priority to Singapore application No. 200200134-5 (filed January 9, 2002) in the above-identified application.

The Examiner is requested to telephone the undersigned Attorney if further information or documentation is required.

Respectfully submitted,

Kristine M. Strodthoff

Dated: May 4, 2007

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